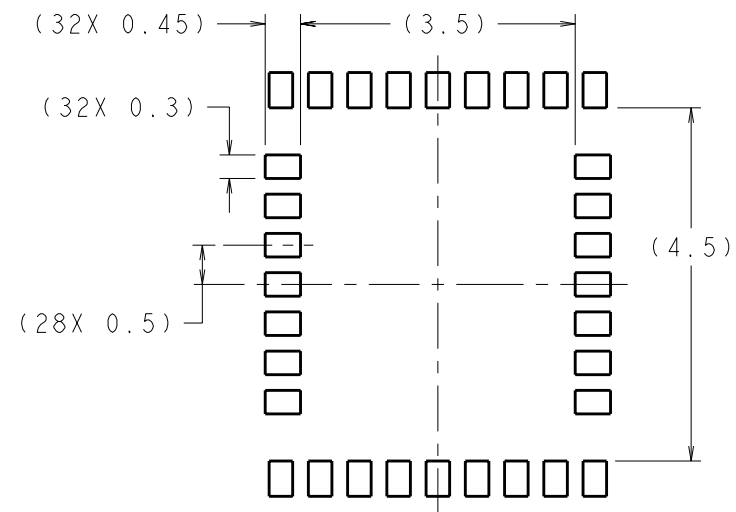
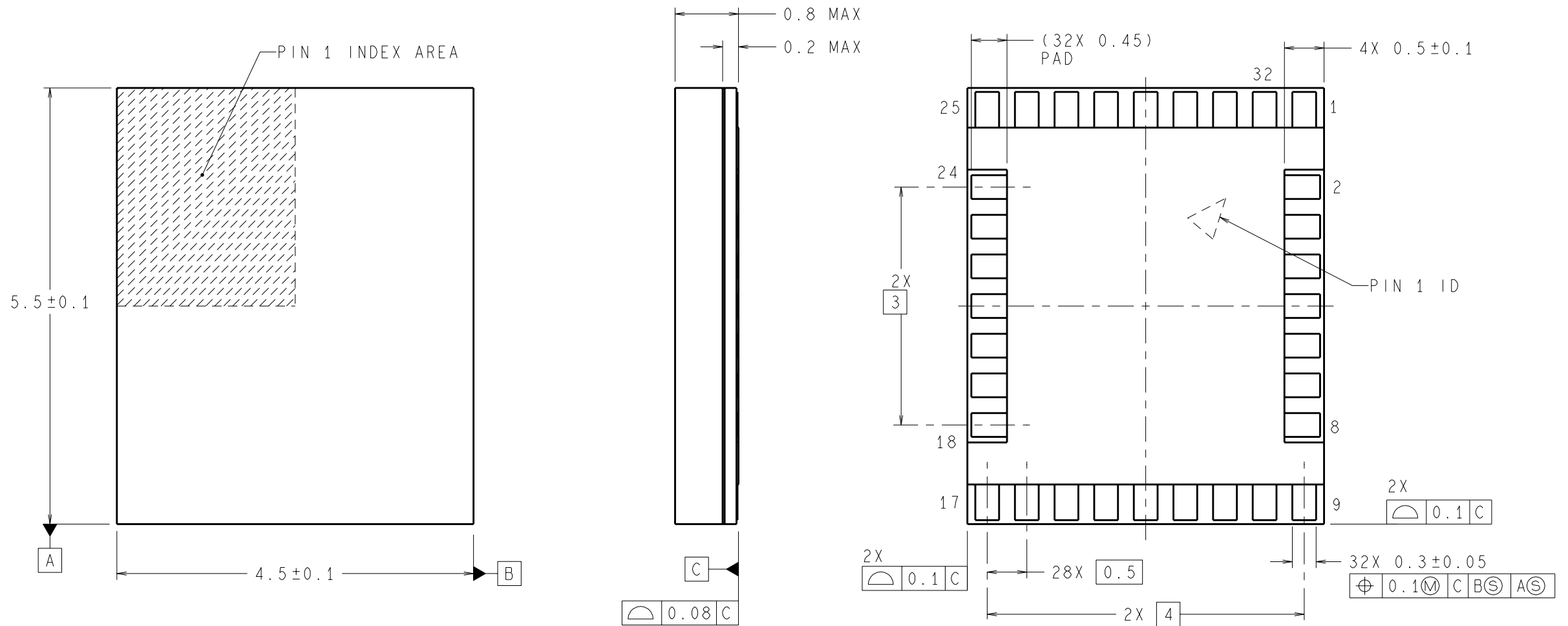


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	115	08/17/2001	TL/AT



RECOMMENDED LAND PATTERN
1:1 RATIO WITH PACKAGE SOLDER PADS

DIMENSIONS ARE IN MILLIMETERS



NOTES: UNLESS OTHERWISE SPECIFIED.

1. MATERIAL: BT RESIN CCL-HL832 WITH TAIYO PSR4000 AUS5 SOLDER MASK.
2. PLATING: Cu 15 TO 20 MICROMETERS (FULL)
Ni 10 ± 5 MICROMETERS (LEADS ONLY)
Au 0.75 ± 0.25 MICROMETER (LEADS ONLY)
3. REFERENCE JEDEC REGISTRATION MO-208, VARIATION GEEA.

APPROVALS		DATE	National Semiconductor		
DRAWN	T. LEQUANG	08/17/2001	2900 Semiconductor Dr., Santa Clara, CA 95052-8090		
DFTG. CHK.	MARTA SUCHY	08/17/2001	THIN CSP, PLASTIC, LAMINATED, 4.5 X 5.5 X 0.8 mm BODY, 32 L, 0.5 mm PITCH		
ENGR. CHK.	ANNY TU	08/17/2001			
PROJECTION		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	(SC)MKT-SLD32A	A
FORMERLY: N/A			SHEET 1 of 1		